

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

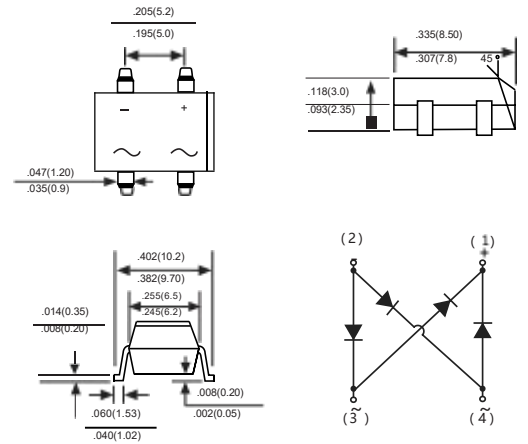
Product data sheet

## Features

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability

## Mechanical Data

- Case** : JEDEC DBS Molded plastic body
- Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity** : Polarity symbol marking on case
- Mounting Position** : Any
- Weight** : 0.02 ounce, 0.4 grams



Dimensions in inches and (millimeters)

## REEL SPECIFICATION

P/N	PKG	QTY
DB201S-DB207S	DBS	1500

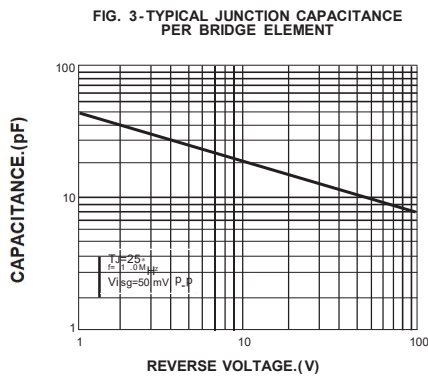
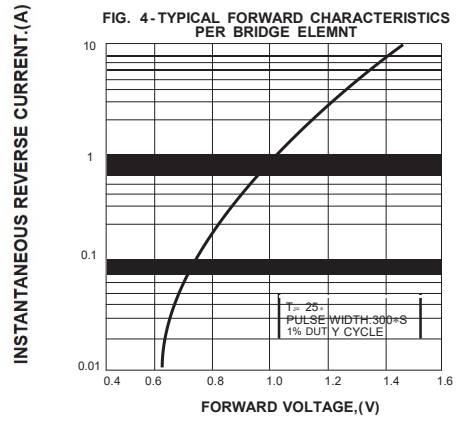
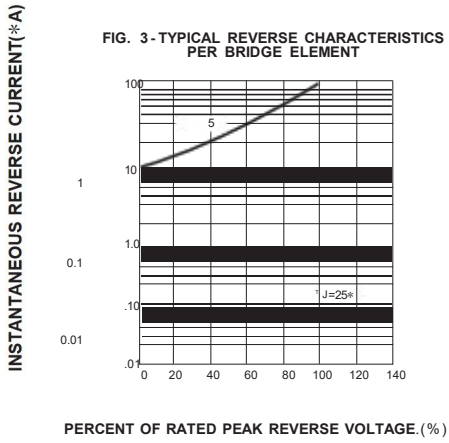
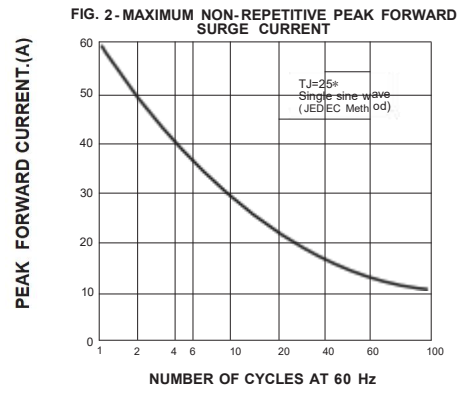
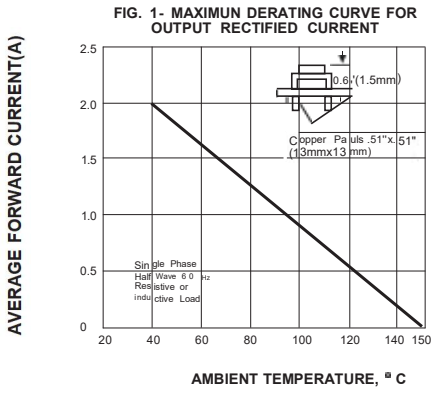
## Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	DB201S	DB202S	DB203S	DB204S	DB205S	DB206S	DB207S	UNITS
		DB201S	DB202S	DB203S	DB204S	DB205S	DB206S	DB207S	
Marking Code		DB201S	DB202S	DB203S	DB204S	DB205S	DB206S	DB207S	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_C=40^\circ C$	$I_{F(AV)}$	2.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	60							A
Maximum instantaneous forward voltage drop per leg at 1A	$V_F$	1.1							V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ C$ $T_A=100^\circ C$	$I_R$	10 500							$\mu A$ $\mu A$
Operating temperature range	$T_J$	-55 to +150							$^\circ C$
storage temperature range	$T_{STG}$	-55 to +150							$^\circ C$

NOTES:DBS for surface mount package.



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